

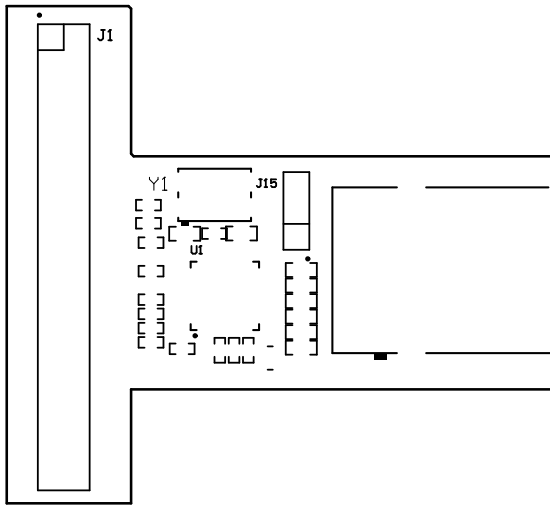
PCB
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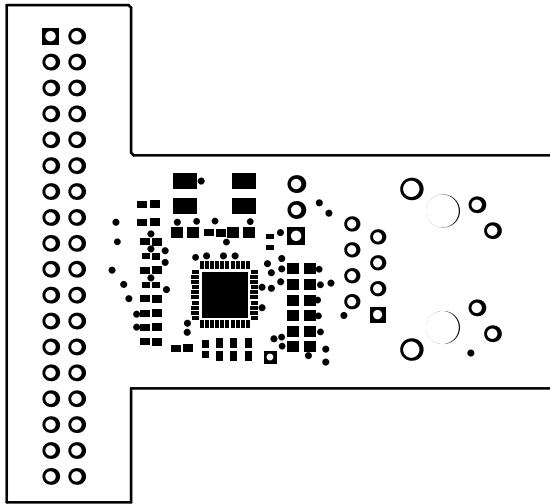
PCB Number: SV012986
PCB Rev: B

Orderable: DP83848K-MAU-EK	Designed for: Public Release	Mod. Date: 1/20/2015	
TLD # : n/a	Project Title: DP83848K-MAU-EK	Sheet Title:	
Number: SV012986	Rev: B	Sheet: 2 of 3	
SVN Rev: Version control disabled	Assembly Variant: 002	Size: C	
Drawn By: Engineer: Matt Dillingham	File: SV012986B_SchDoc	Contact: http://www.ti.com/support	

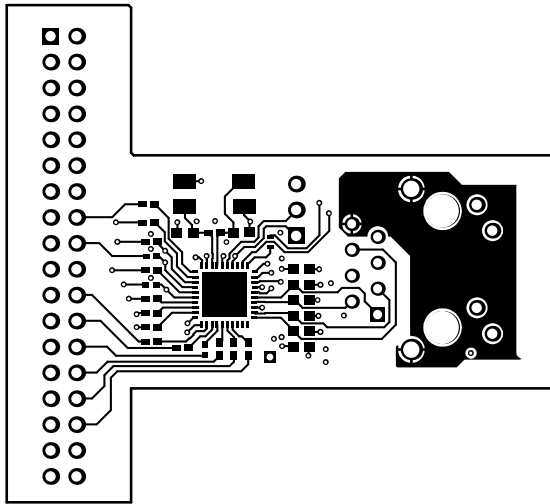
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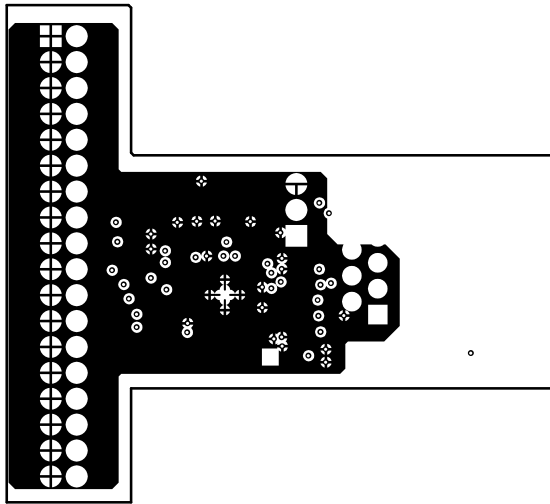
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU012986	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/9/2016	3:08:59 PM	TEXAS INSTRUMENTS



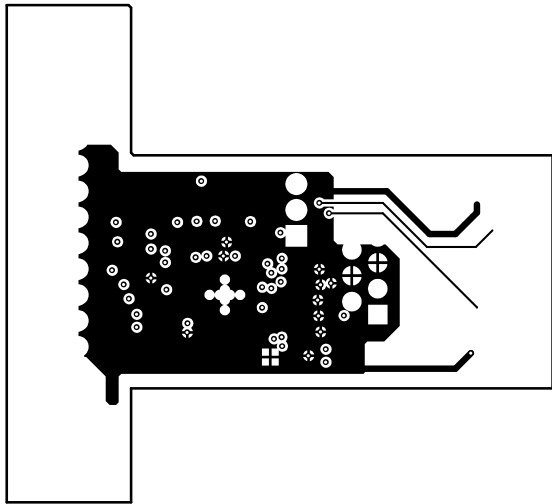
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/9/2016 3:08:59 PM	TEXAS INSTRUMENTS	



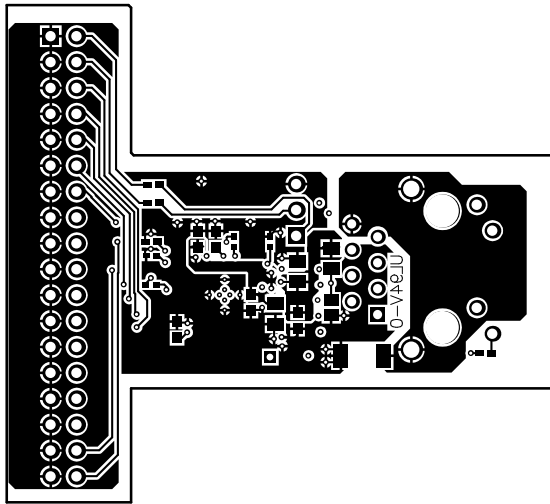
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU012986	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/9/2016 3:09:00 PM	TEXAS INSTRUMENTS	



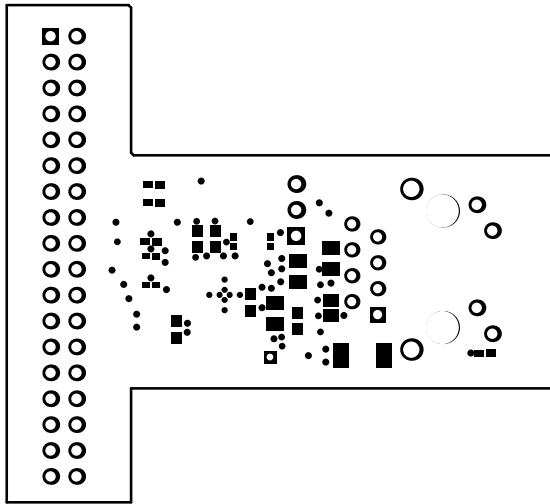
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LAYER NAME = M1 Board Outline			
PLOT NAME = Mid-Layer 1	GENERATED : 3/9/2016 3:09:01 PM	TEXAS INSTRUMENTS	



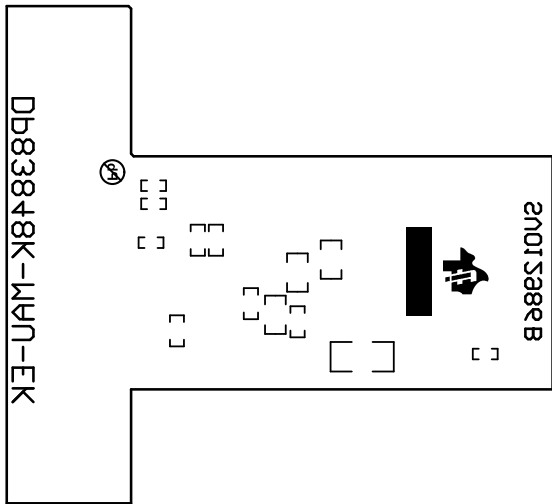
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LAYER NAME = M1 Board Outline			
PLOT NAME = Mid-Layer 2	GENERATED : 3/9/2016 3:09:02 PM	TEXAS INSTRUMENTS	



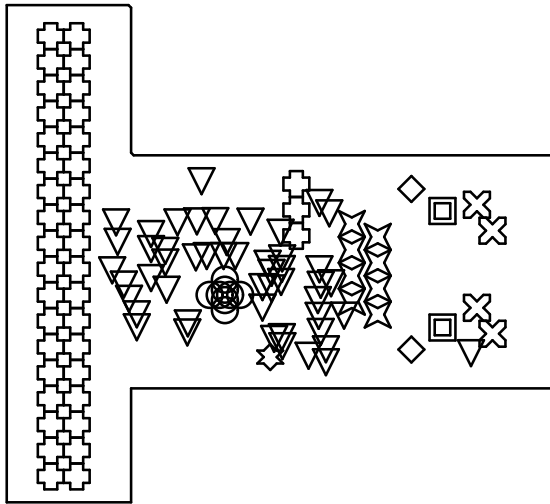
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU012986	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/9/2016 3:09:03 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU012986	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/9/2016 3:09:04 PM	TEXAS INSTRUMENTS	

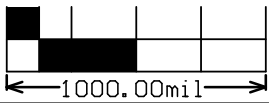
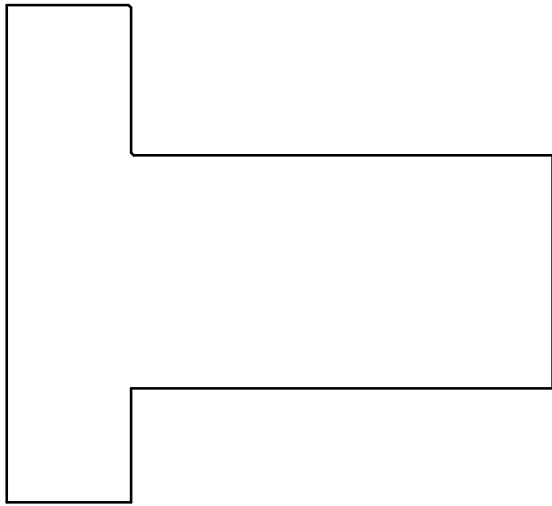


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU012986	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/9/2016	3:09:04 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
■	2	127.95mil (3.250mm)	NPTH	Round
○	8	7.87mil (0.200mm)	PTH	Round
▽	50	12.00mil (0.305mm)	PTH	Round
⊗	1	26.00mil (0.660mm)	PTH	Round
⊗	8	35.04mil (0.890mm)	PTH	Round
⊗	39	40.00mil (1.016mm)	PTH	Round
⊗	4	40.16mil (1.020mm)	PTH	Round
◇	2	62.99mil (1.600mm)	PTH	Round
	114 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU012986	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/9/2016	3:09:05 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU012986	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/9/2016 3:09:06 PM	TEXAS INSTRUMENTS	

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